# CLAIMS

[Claim 1] A substrate processing system comprising:

a substrate information acquiring unit configured to acquire substrate information including position information of a structure which is located above a surface of a first substrate; and

a determination unit configured to determine an exposure condition for exposing a second substrate which is bonded to the first substrate to light on the basis of the acquired substrate information.

[Claim 2] The substrate processing system according to claim 1, comprising a computation apparatus including the substrate information acquiring unit and the determination unit.

[Claim 3] The substrate processing system according to claim 1 or 2, further comprising a measuring apparatus for measuring position information of the structure,

wherein the substrate information acquiring unit acquires the substrate information including the position information measured by the measuring apparatus.

[Claim 4] The substrate processing system according to claim 3, further comprising a first exposure apparatus for exposing the first substrate to light,

wherein the measuring apparatus measures position information of the structure formed by causing the first exposure apparatus to expose a layer of photosensitive material layer above the surface of the first substrate to light.

[Claim 5] The substrate processing system according to claim 4, further comprising a second exposure apparatus for exposing the second substrate to light, the second exposure apparatus being different from the first exposure apparatus,

wherein the second exposure apparatus exposes the second substrate to light on the basis of the substrate information including the position information of the structure.

[Claim 6] The substrate processing system according to any one of claims 1 to 5, wherein the second substrate includes a plurality of layers, and

wherein the determination unit determines the exposure condition for exposing an uppermost layer of the second substrate to light.

[Claim 7] The substrate processing system according to any one of claims 1 to 6, wherein the second substrate includes a plurality of layers, and

wherein the determination unit determines the exposure condition for exposing a lower layer of the second substrate to light.

[Claim 8] The substrate processing system according to claim 6 or 7, wherein the determination unit determines a plurality of exposure conditions for exposing the plurality of layers of the second substrate to light.

[Claim 9] The substrate processing system according to any one of claims 1 to 8, further comprising a pre-correction exposure pattern acquiring unit configured to acquire preset pre-correction exposure patterns of the first substrate and the second substrate,

wherein the determination unit determines a post-correction exposure pattern by correcting the pre-correction exposure pattern on the basis of the substrate information.

[Claim 10] The substrate processing system according to claim 9, further comprising a comparison unit configured to compare wiring information included in the exposure condition with a predetermined threshold value,

wherein the determination unit identifies a layer to be corrected out of a plurality of layers included in the second substrate on the basis of a result of comparison from the comparison unit and determines the post-correction exposure pattern to be formed in the identified layer.

[Claim 11] The substrate processing system according to claim 8 or 9, wherein the determination unit determines the exposure condition for exposing a first layer out of a

plurality of layers included in the second substrate to light and the exposure condition for exposing a second layer above the first layer to light, and

wherein a correction value for the first layer is greater than a correction value for the second layer.

[Claim 12] The substrate processing system according to claim 1, wherein the substrate information acquiring unit acquires first substrate information including the position information of the structure and third substrate information including position information of a structure formed on a third substrate other than the first substrate, and

wherein the determination unit determines an exposure condition based on the first substrate information for a first surface of the second substrate and determines an exposure condition based on the third substrate information for a second surface which is an opposite surface of the first surface.

[Claim 13] The substrate processing system according to claim 12, wherein the second substrate is an interposer for bonding the first substrate and the third substrate.

[Claim 14] The substrate processing system according to claim 1, further comprising a pre-correction exposure pattern acquiring unit configured to acquire a preset pre-correction first exposure pattern of the first substrate and a pre-correction second exposure pattern which is a preset exposure pattern of the second substrate,

wherein the structure includes a reference grid formed on a reference substrate, and

wherein the determination unit determines a post-correction first exposure pattern by correcting the pre-correction first exposure pattern on the basis of the reference grid and determines a post-correction second exposure pattern by correcting the pre-correction second exposure pattern on the basis of the reference grid.

[Claim 15] The substrate processing system according to claim 14, wherein the

reference grid includes a first reference grid for correcting the exposure condition for exposing the first substrate to light and a second reference grid for correcting the exposure condition for exposing the second substrate to light, and

wherein the second reference grid is a mirror image of the first reference grid.

[Claim 16] The substrate processing system according to claim 14 or 15, wherein the first substrate and the second substrate include a plurality of layers, and

wherein the determination unit performs control for exposing the plurality of layers of the first substrate and the plurality of layers of the second substrate to light.

[Claim 17] The substrate processing system according to any one of claims 1 to 16, wherein the determination unit determines the exposure condition additionally on the basis of a predetermined approximate expression.

[Claim 18] The substrate processing system according to any one of claims 1 to 17, further comprising a stacking apparatus for overlapping the first substrate and the second substrate.

[Claim 19] An exposure apparatus comprising an exposure control unit configured to expose a second substrate which is bonded to a first substrate to light on the basis of a substrate information including position information of a structure located above a surface of the first substrate.

[Claim 20] A processing method comprising:

acquiring substrate information including position information of a structure which is located above a surface of a first substrate; and

determining an exposure condition for exposing a second substrate which is bonded to the first substrate to light on the basis of the acquired substrate information.

[Claim 21] An exposure method comprising exposing a second substrate which is bonded to a first substrate to light on the basis of an exposure condition which is

determined by the processing method according to claim 20.

[Claim 22] An electronic device manufacturing method comprising:

an exposure method according to claim 21;

exposing the second substrate to light on the basis of the determined exposure condition; and

a stacking step of overlapping the first substrate and the second substrate.